

N-Channel Enhancement Mode Field Effect Transistor

- Features**

20V/5A

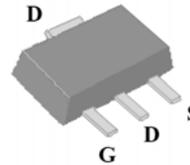
$R_{DS(ON)} = 28m\ \Omega$ @ $V_{GS} = 4.5V$

$R_{DS(ON)} = 38m\ \Omega$ @ $V_{GS} = 2.5V$

Low $V_{GS(TH)}$

SOT89 Package

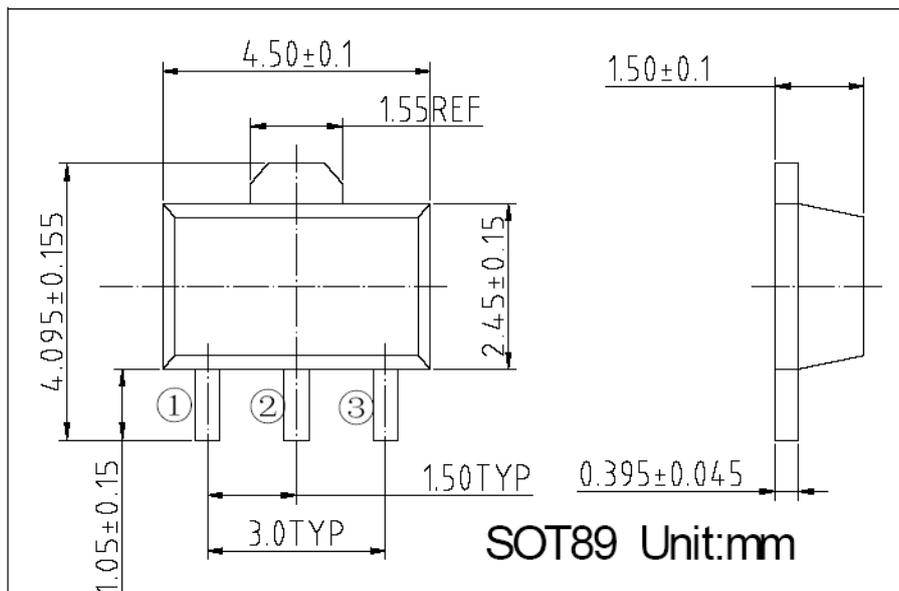
- Pin Configurations**



- General Description**

The RCR1515SM uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications. RCR1515SM are electrically identical. -RoHS Compliant

- Package Information**



- Absolute Maximum Ratings @ $T_A=25^\circ C$ unless otherwise noted**

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		V_{DSS}	20	V
Gate-Source Voltage		V_{GSS}	± 12	V
Drain Current (Continuous)	$T_A=25^\circ C$	I_D	5	A
	$T_A=70^\circ C$		4	
Drain Current (Pulse)		I_{DM}	20	A
Power Dissipation	$T_A=25^\circ C$	P_D	1	W
	$T_A=70^\circ C$		0.7	



RCR1515SM

Operating Temperature/ Storage Temperature	T_J/T_{STG}	-55~150	°C
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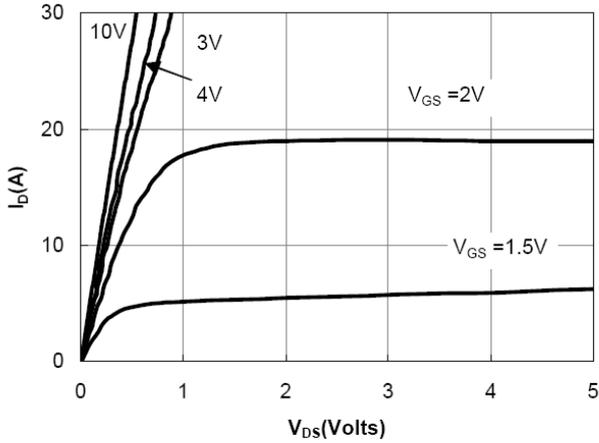
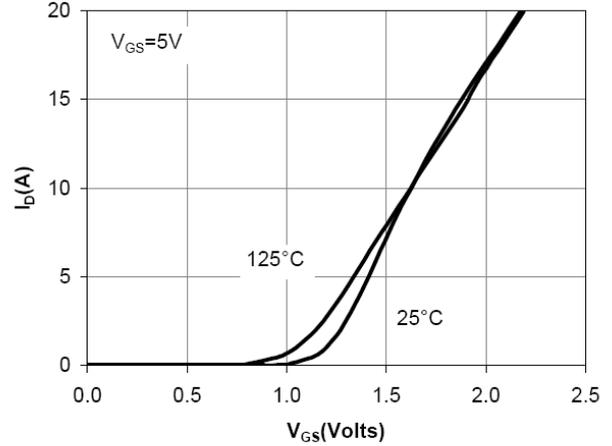
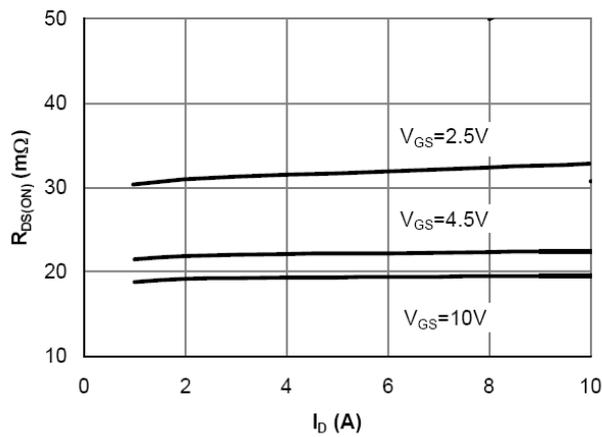
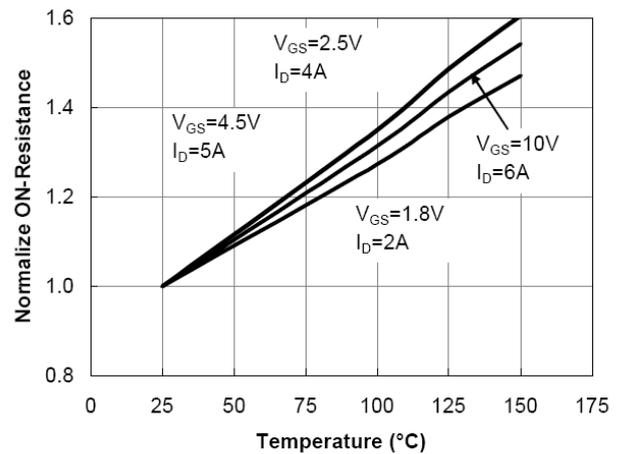
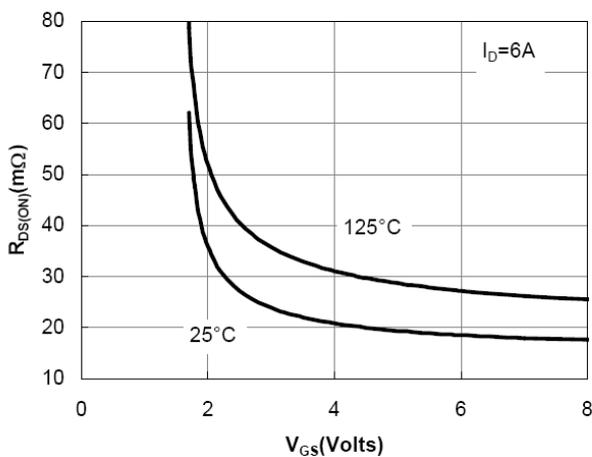
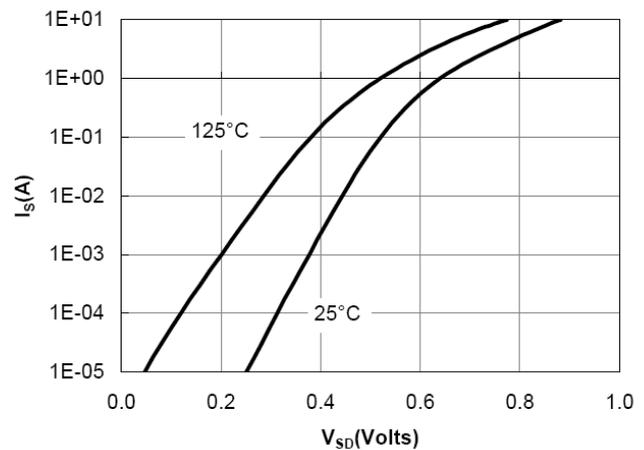
● **Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise noted**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250 \mu A$	20	25	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$	--	--	1	μA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_{DS} = 250 \mu A$	0.6	0.84	1	V
Gate Leakage Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$	--	--	100	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 3A$	--	23	28	$m\Omega$
		$V_{GS} = 2.5V, I_D = 2A$	--	31	38	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS} = 10V, I_D = 6A$	--	5	--	S
Diode Forward Voltage	V_{SD}	$I_{SD} = 1A, V_{GS} = 0V$	--	0.71	1.0	V
Maximum Body-Diode Continuous Current	I_S		--	--	1.7	A
Pulsed Body-Diode Current	I_{SM}		--	--	20	A
Switching						
Total Gate Charge	Q_g	$V_{GS} = 4.5V, V_{DS} = 10V, I_D = 6A$	--	6.3	8.1	nC
Gate-Source Charge	Q_{GS}		--	1.7	2.2	nC
Gate-Drain Charge	Q_{GD}		--	1.4	1.8	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 10V, I_D = 1A, V_{GS} = 4.5V, R_G = 6\Omega$	--	10.4	20.8	ns
Turn-on Rise Time	t_r		--	4.4	8.8	ns
Turn-off Delay Time	$t_{d(off)}$		--	27.4	54.8	ns
Turn-off Fall Time	t_f		--	4.2	8.4	ns
Dynamic						
Input Capacitance	C_{iss}	$V_{DS} = 8V, V_{GS} = 0V, F = 1.0MHz$	--	522.3	--	pF
Output Capacitance	C_{oss}		--	98.5	--	pF
Reverse Transfer Capacitance	C_{rss}		--	74.7	--	pF

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The current rating is based on the $t_s \leq 10s$ junction to ambient thermal resistance rating.

● Typical Performance Characteristics

Figure 1: On-Regions Characteristic CS

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

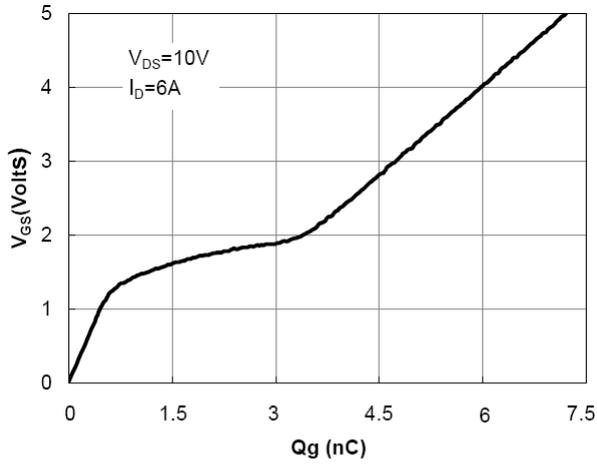


Figure 7: Gate-Charge Characteristics

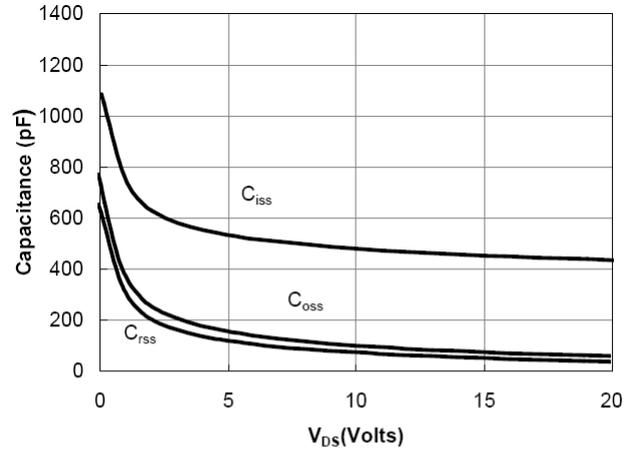


Figure 8: Capacitance Characteristics

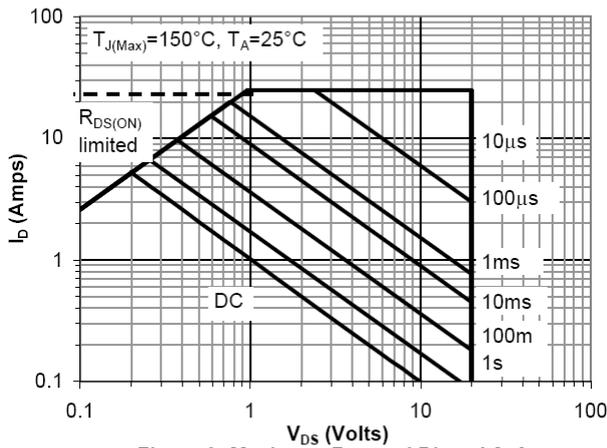


Figure 9: Maximum Forward Biased Safe Operating Area

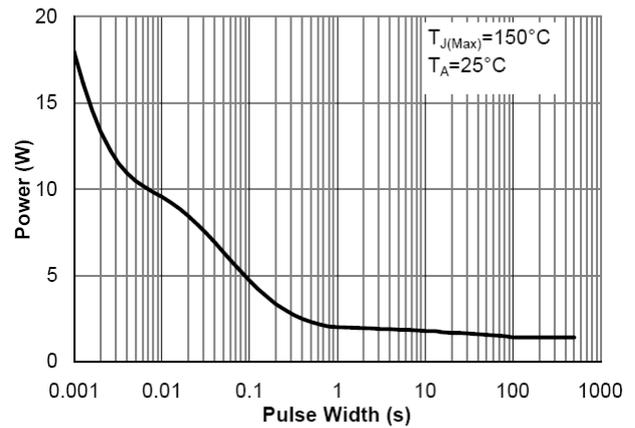


Figure 10: Single Pulse Power Rating Junction-to-Ambient

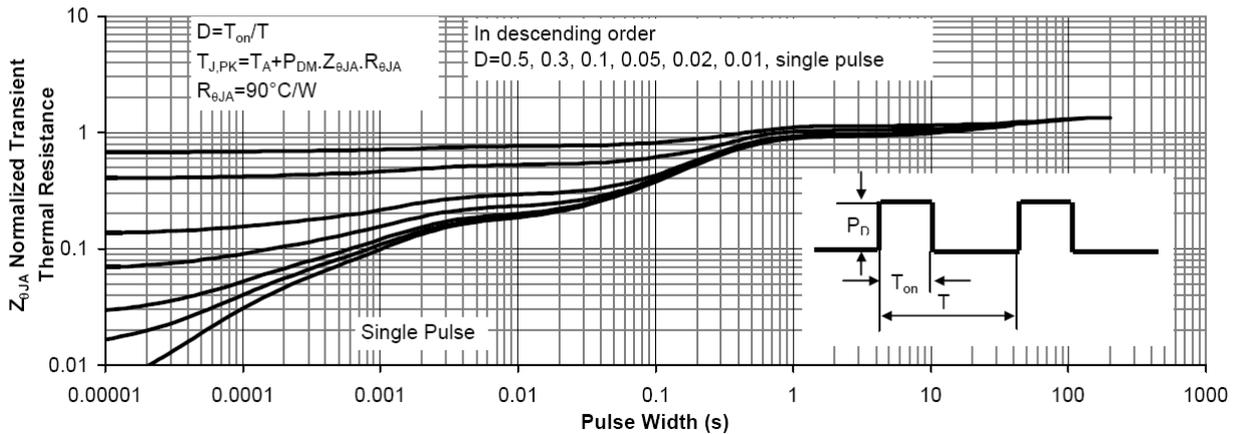


Figure 11: Normalized Maximum Transient Thermal Impedance



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